

AGH



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Hotel Sepetná,
Ostravice



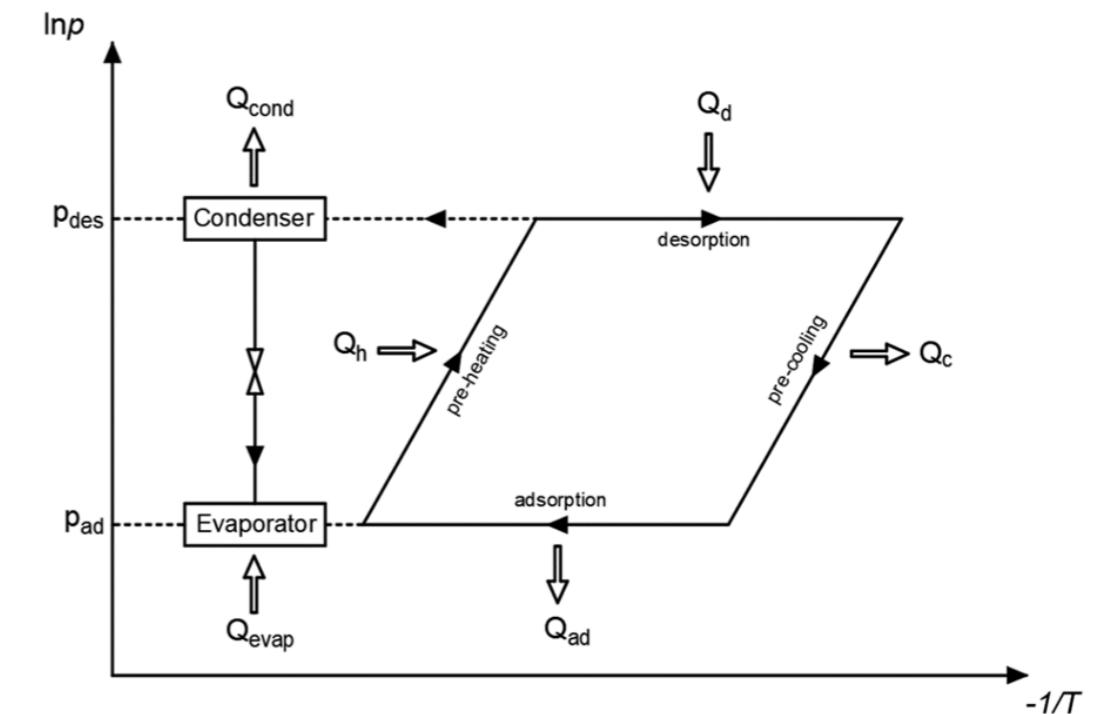
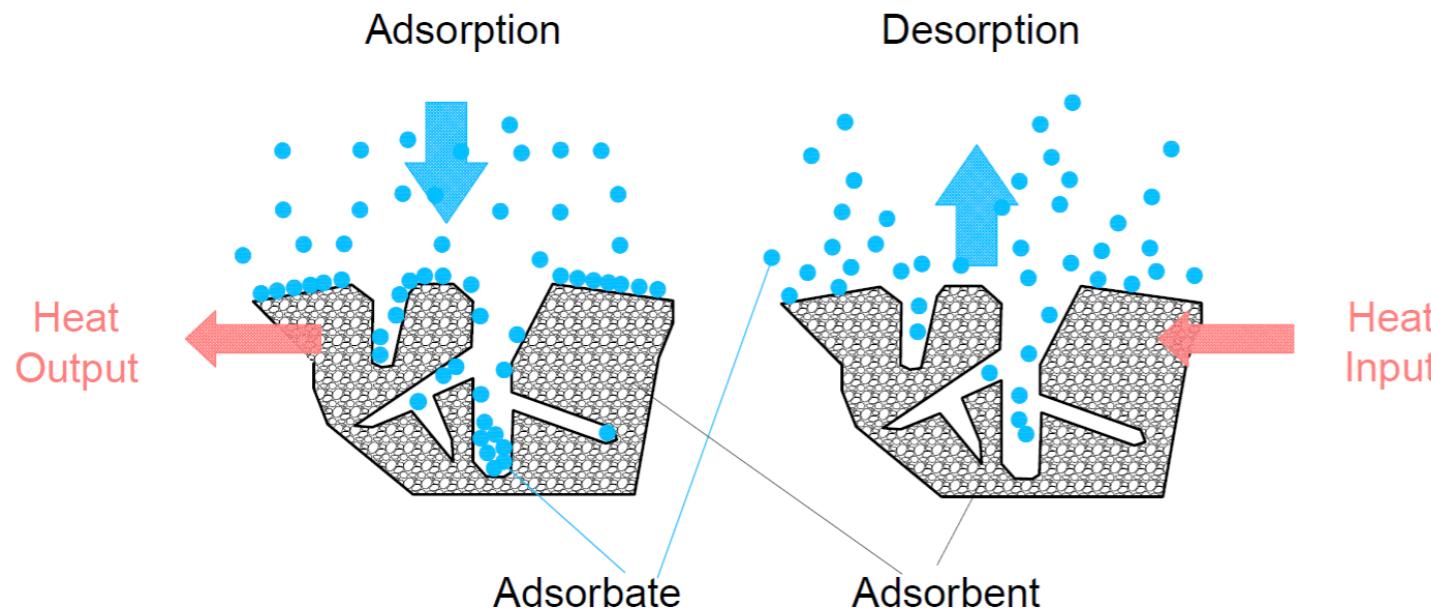
Coated Adsorption Beds for Enhanced Heat Transfer in Adsorption Cooling Systems

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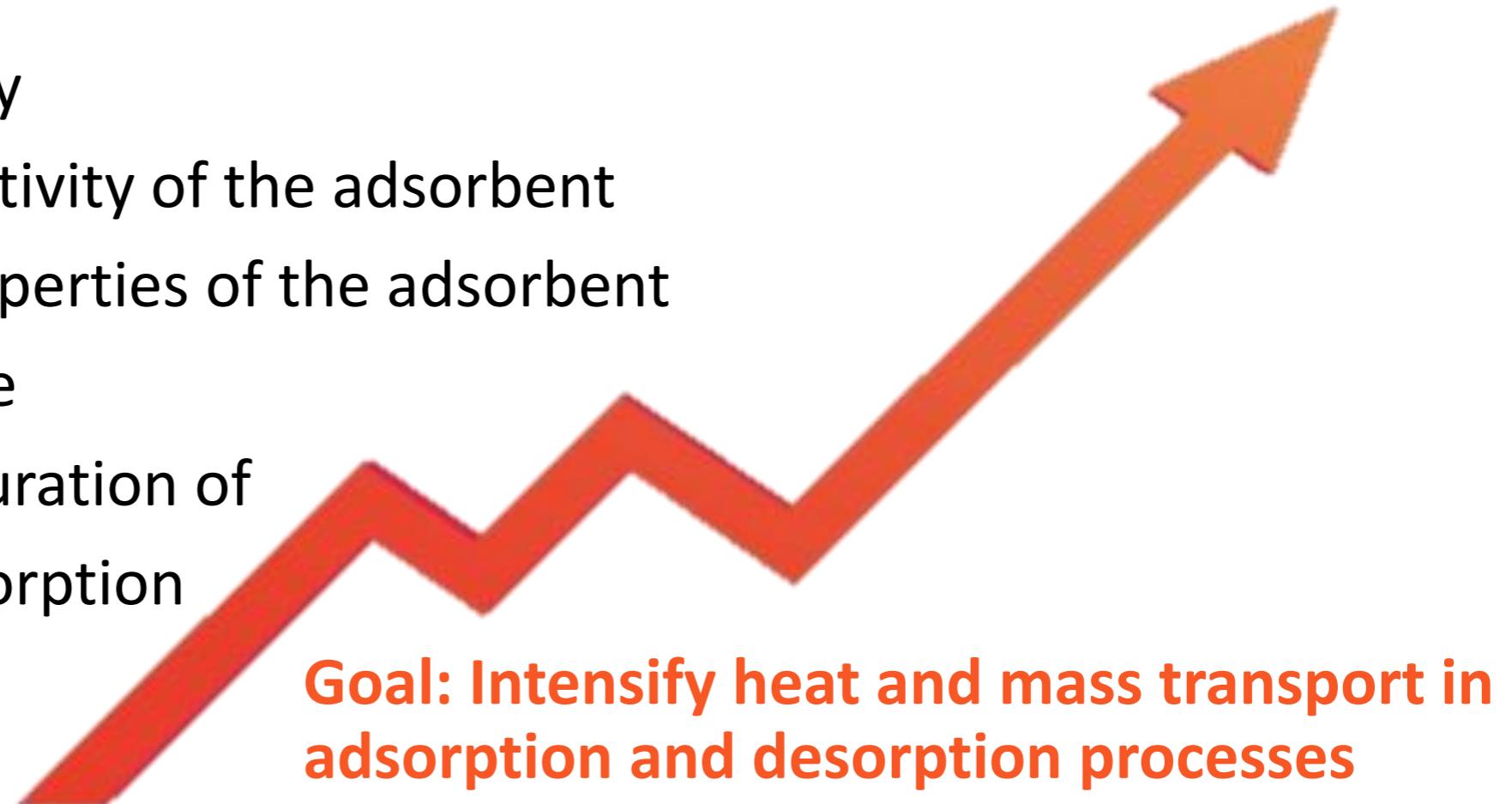
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Adsorption chillers

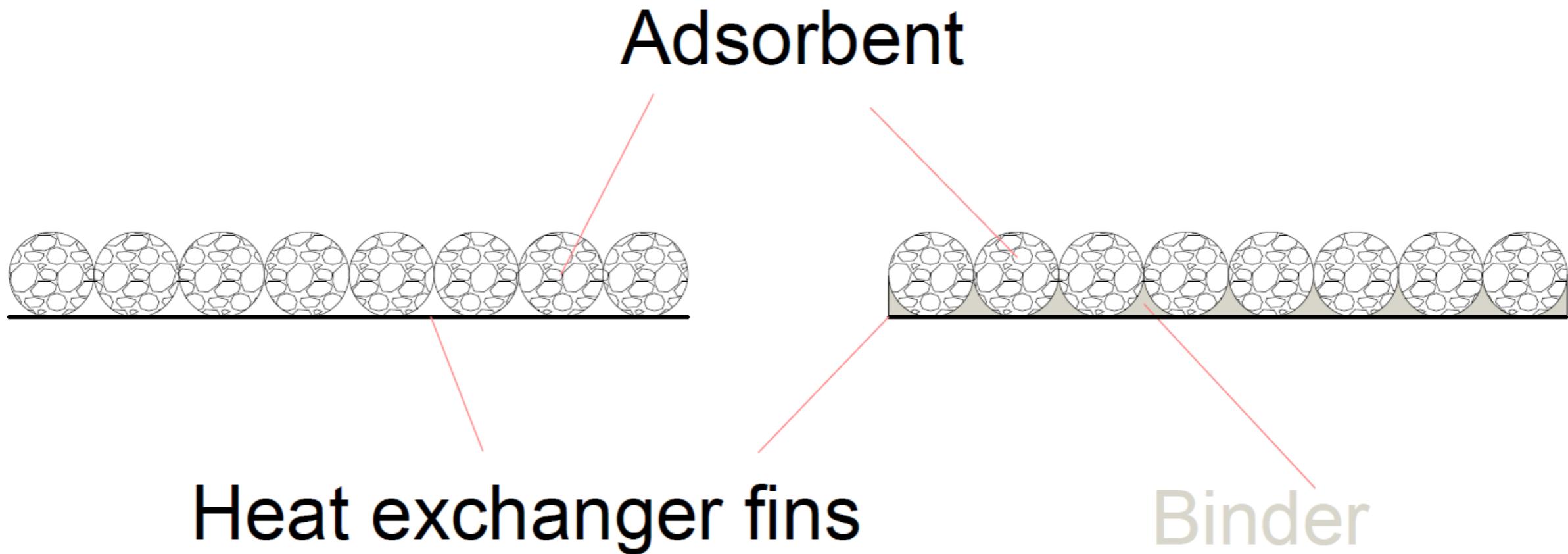


Motivation of the research

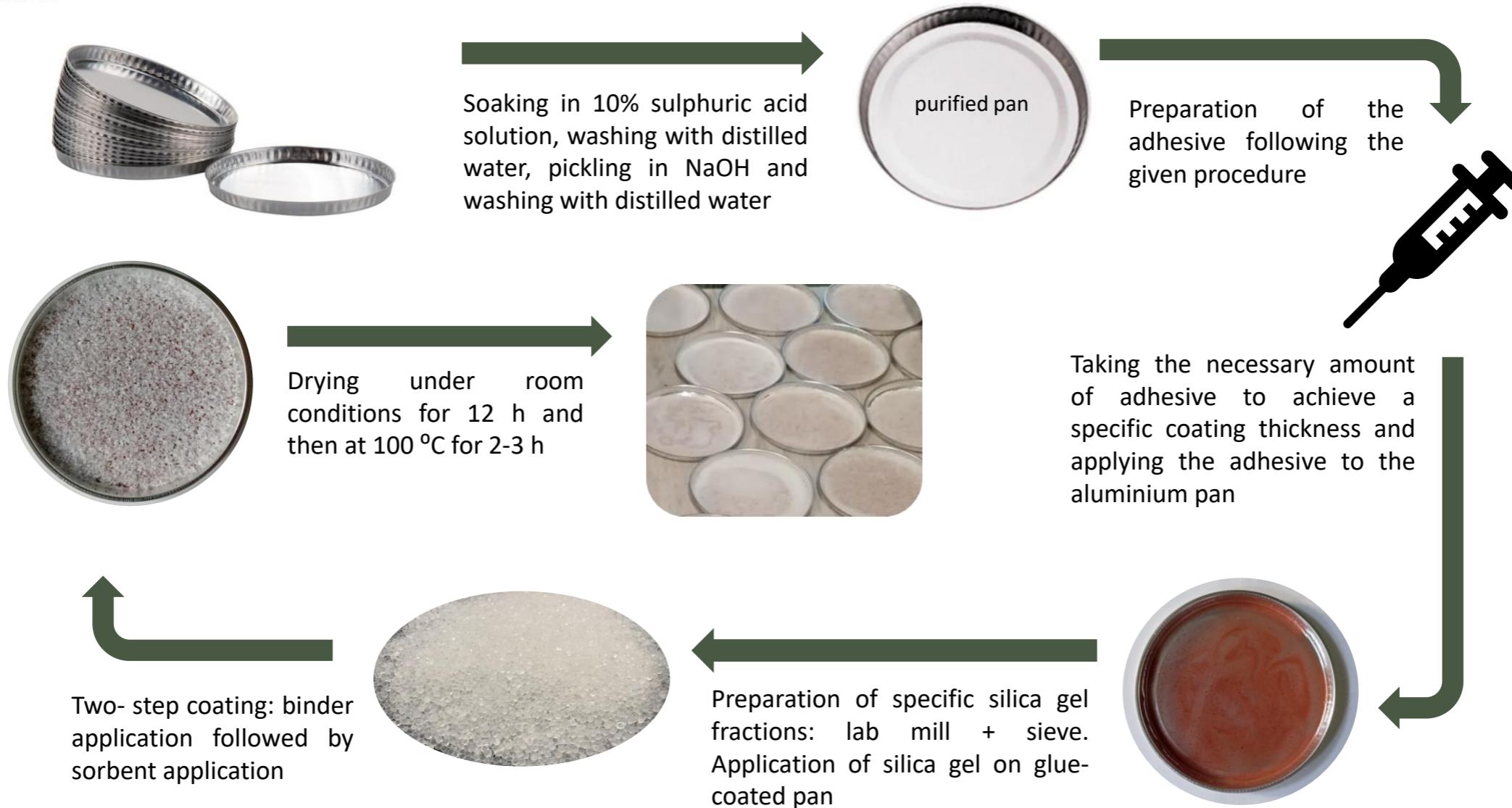
- Low chiller efficiency
- low thermal conductivity of the adsorbent
- limited sorption properties of the adsorbent
- large equipment size
- differences in the duration of adsorption and desorption processes



Binder as Solution - Maybe



Preparing bonded samples



Methods

DSC

DSC 214 Polyma
Differential scanning calorimetry,
Specific heat determination



LFA

NETZSCH LFA 467 HyperFlash
Thermal diffusivity and
conductivity coefficient



TGA

Mettler Toledo TGA-DSC 3+
Heating rate: 10 K/min
Thermal stability

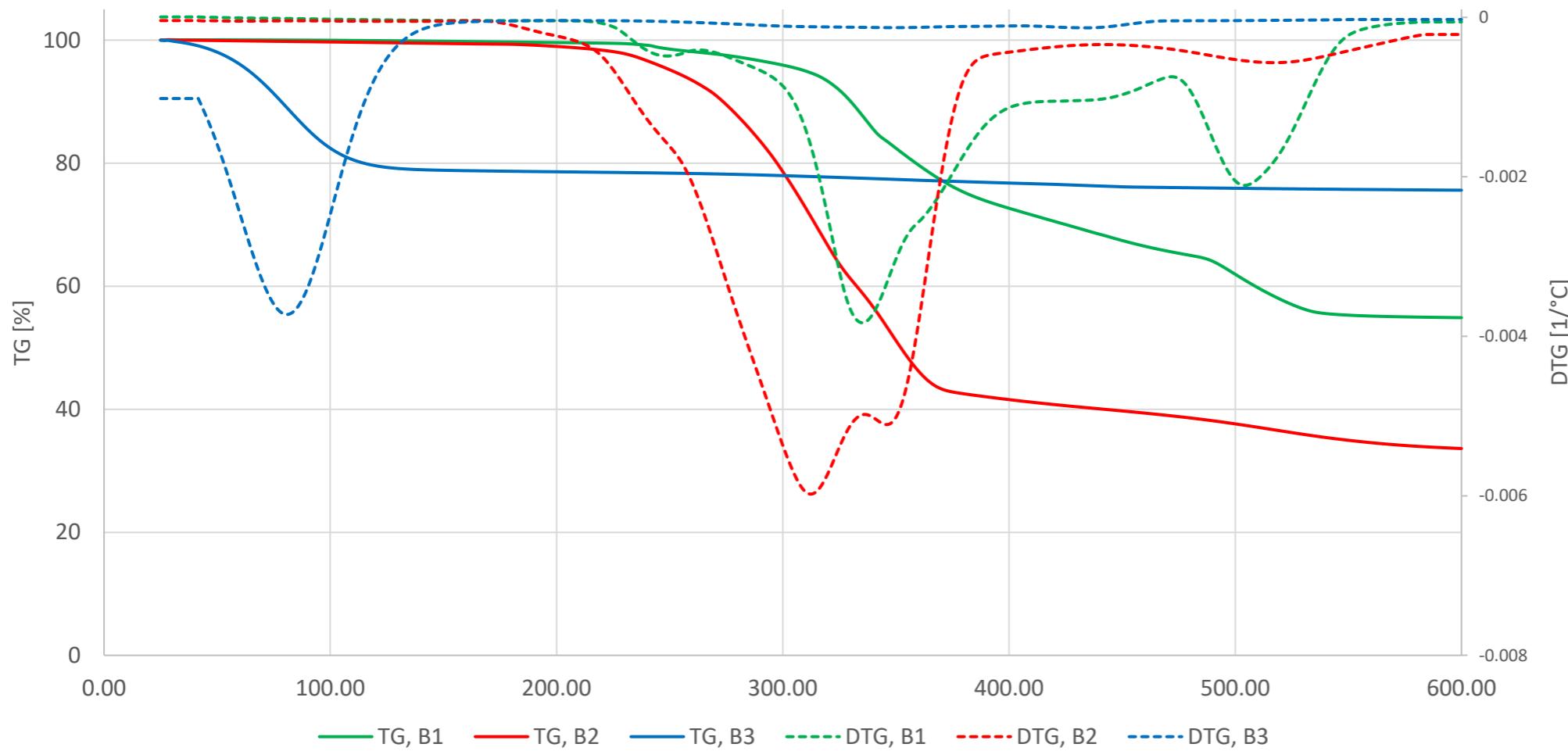


DVS

DVS Vacuum, Gravimetric Vapor
Sorption Analyzer
Sorption isotherms and kinetics



Thermal stability



B1 – based on epoxy resin and graphite flakes

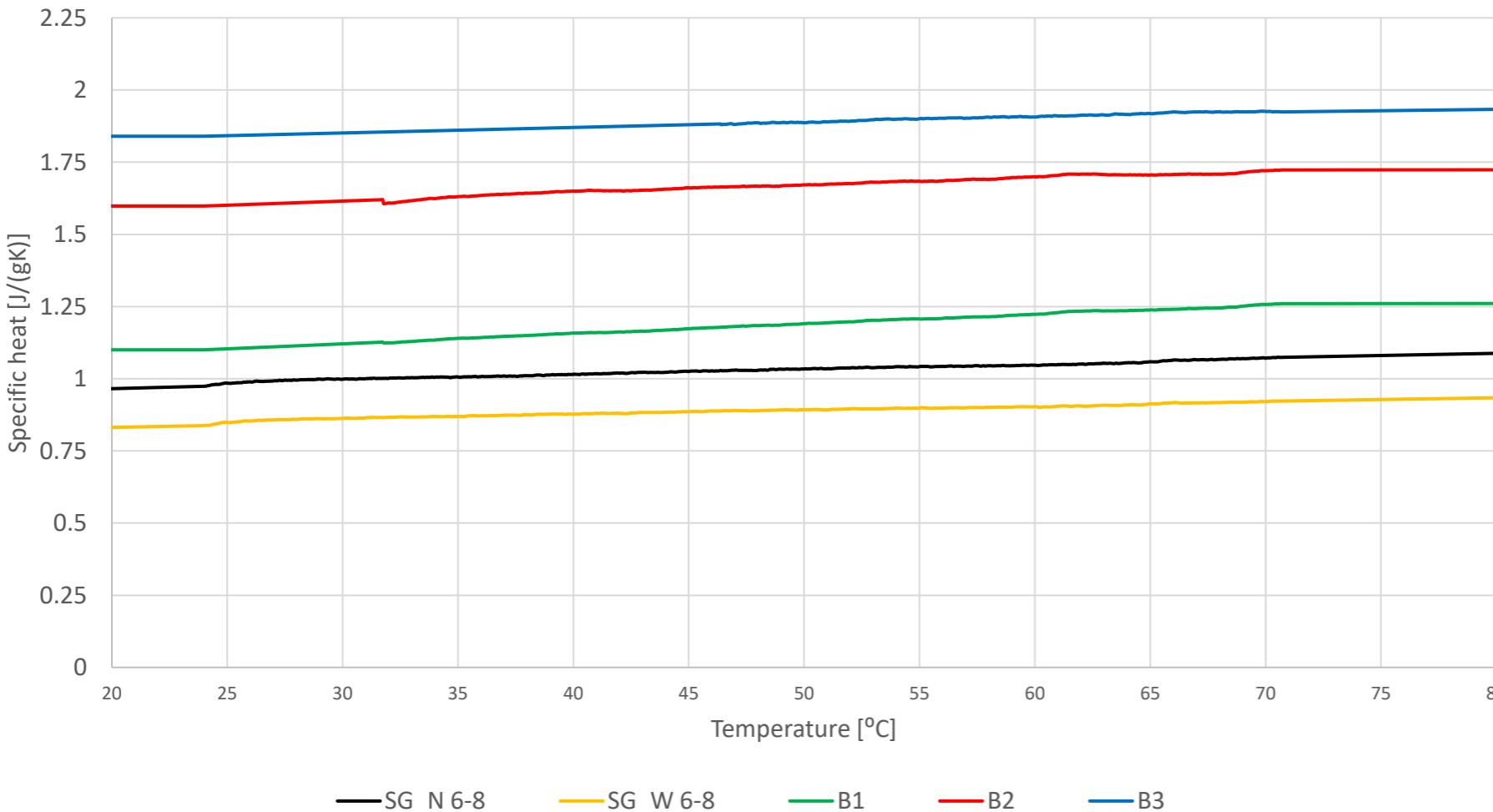


B2 – based on polyurethane resin and graphite flakes

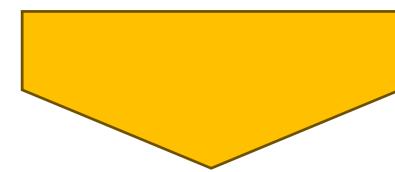


B3 – based on PVA and graphite flakes

Specific heat determination

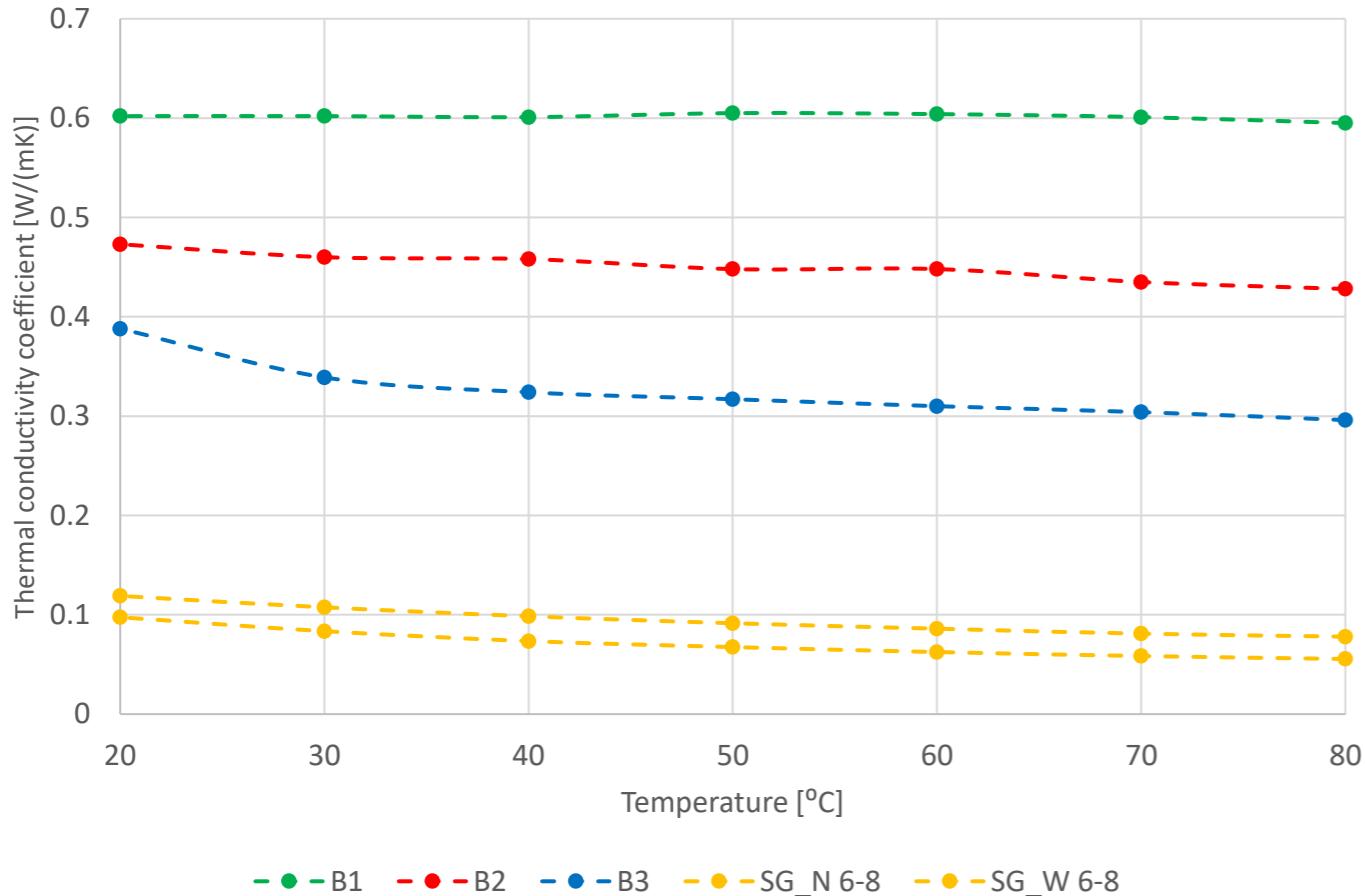


- B1 adhesive (based on epoxy resin and graphite flakes) has a specific heat similar to silica gel.



- uniform heating of the sorption bed

Thermal conductivity



$$\lambda(T) = \alpha(T) \cdot \rho(T) \cdot c_p(T)$$

B1 – based on epoxy resin
 B2 – based on polyurethane resin
 B3 – based on PVA

LFA samples holders
 Samples were graphite-coated
 Sample h=1,5mm Ø=14,8 mm



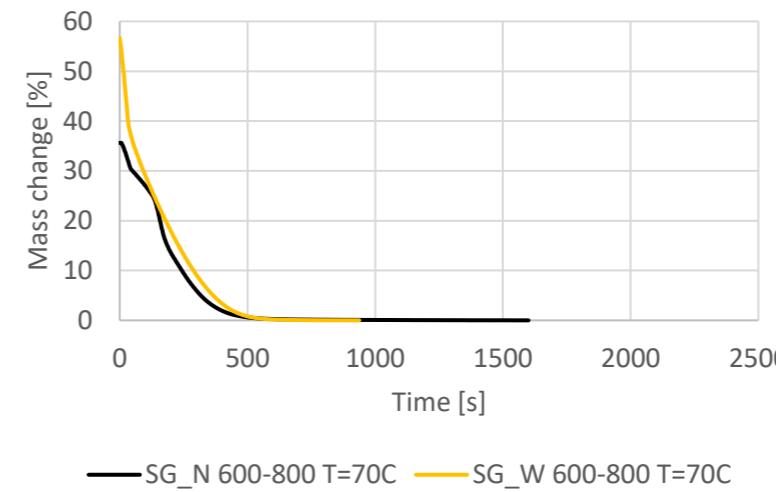
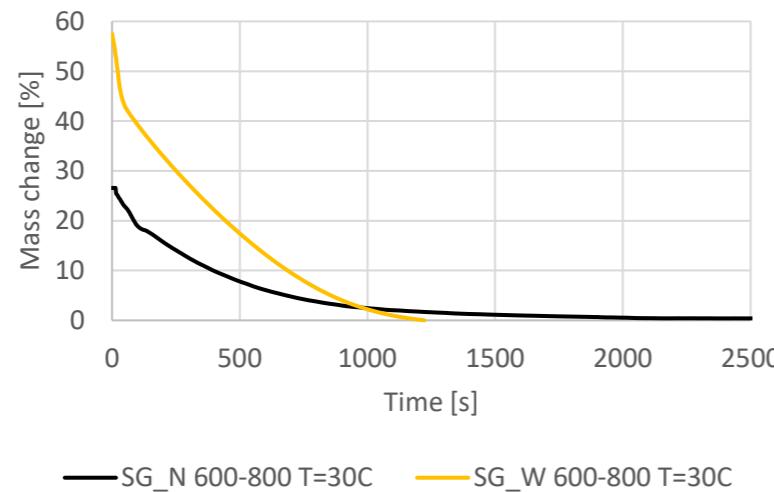
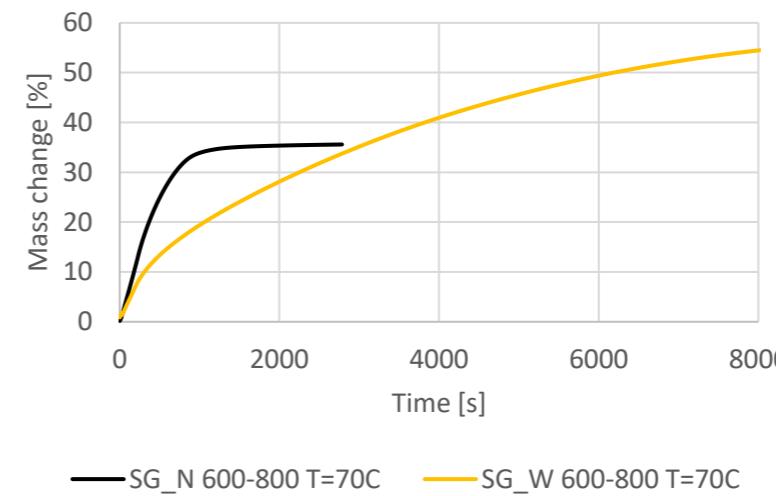
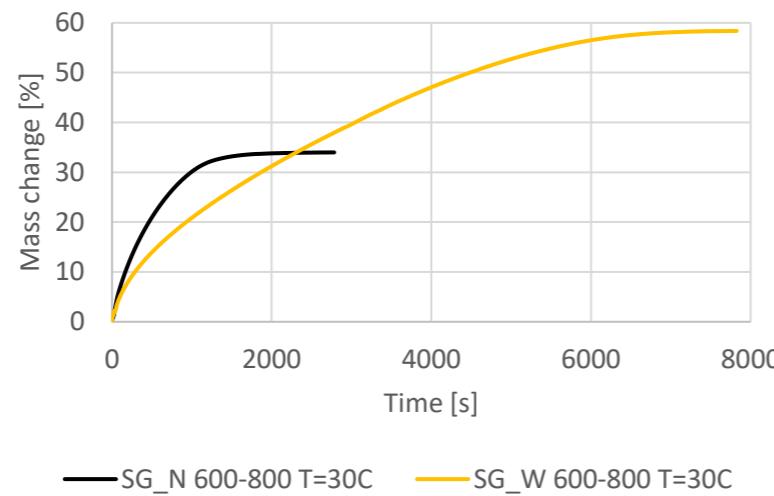
Figure 3. Thermal conductivity coefficient of adhesives and sorbents.

Thermal conductivity

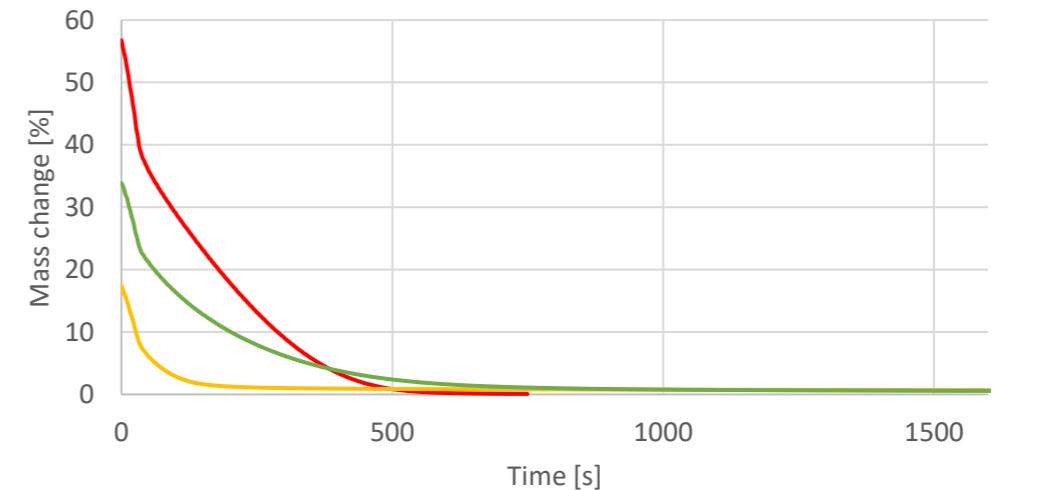
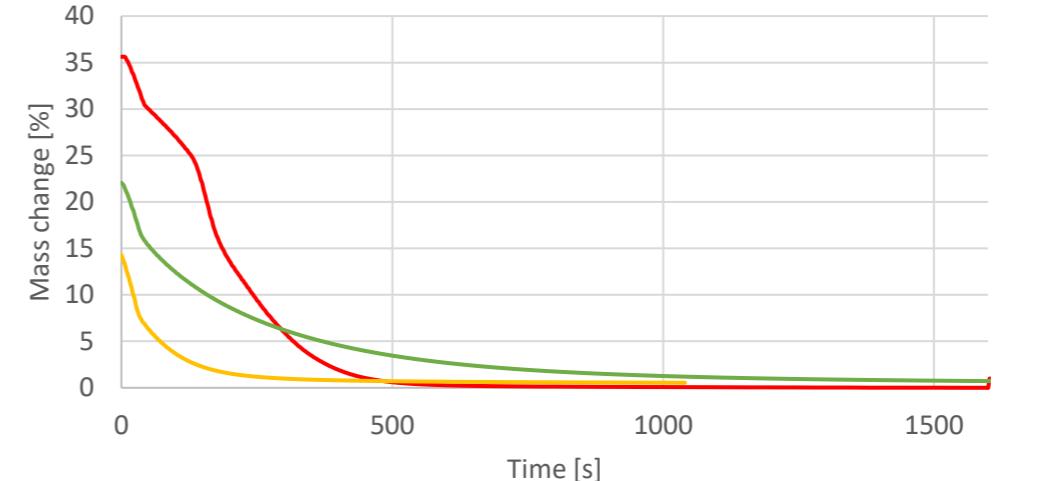
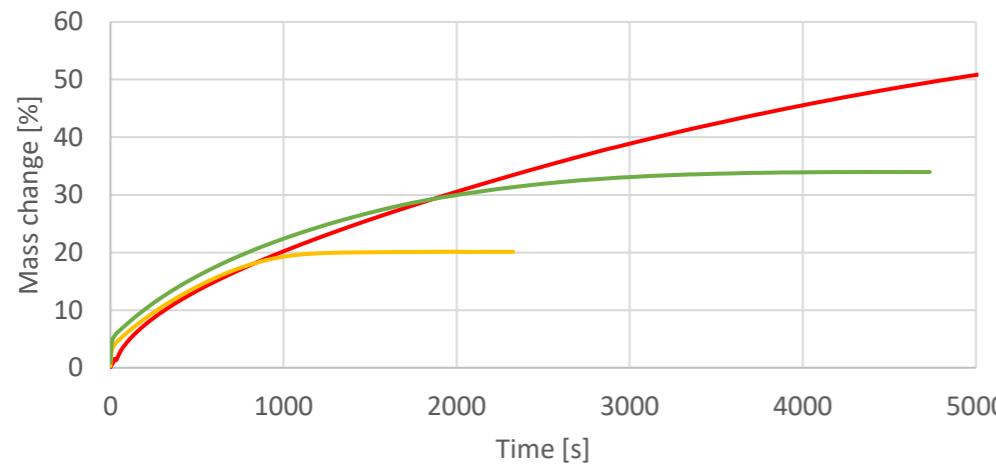
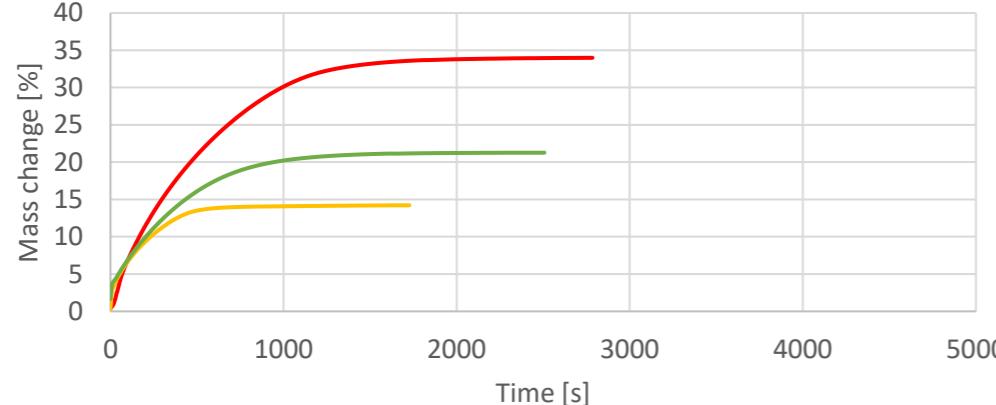


Temperature	[°C]	20	30	40	50	60	70	80
Thermal conductivity of SG_N 6-8	[W/(mK)]	0,078	0,081	0,086	0,092	0,099	0,108	0,119
Thermal conductivity of SG_N 6-8 + B1	[W/(mK)]	0,216	0,224	0,230	0,240	0,252	0,263	0,272
Improvement	[%]	177	176	167	162	155	145	128
Thermal conductivity of SG_N 6-8 + B2	[W/(mK)]	0,175	0,180	0,187	0,192	0,198	0,207	0,214
Improvement	[%]	124	122	117	108	99	91	79
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Thermal conductivity of SG_W 6-8	[W/(mK)]	0,056	0,059	0,063	0,068	0,074	0,084	0,098
Thermal conductivity of SG_W 6-8 + B1	[W/(mK)]	0,397	0,399	0,402	0,402	0,399	0,395	0,387
Improvement	[%]	614	581	542	495	443	373	297
Thermal conductivity of SG_W 6-8 + B2	[W/(mK)]	0,165	0,168	0,170	0,173	0,177	0,182	0,188
Improvement	[%]	195	184	169	154	139	117	91

Sorption kinetics results



Sorption kinetics results





Conclusions

- ✓ Appropriate preparation of aluminum pans and the use of two-step coating almost completely eliminate the problem of detachment of the binder from the aluminum.
- ✓ Adhesives B1 and B2 (resin-based) demonstrate thermal stability up to 200 °C, making them suitable for use in adsorption chillers. In contrast, PVA-based adhesive B3 shows a 20% mass loss between 20–100 °C due to water sorption and desorption.
- ✓ Thermal properties measurements indicate graphite flakes as the best thermally conductive binder additive.
- ✓ Epoxy resin-based adhesive doped with graphite flakes allows to improve the thermal conductivity of the sorbent by 177% and 614% with respect to SG_N and SG_W, respectively.
- ✓ Silica gels combined with adhesives B1 and B2 exhibit more intensive sorption kinetics during the initial 100 seconds of the cycle compared to raw silica gels.
- ✓ The use of thermally conductive binders may enable the chiller to operate with shorter cycle times or lower the desorption temperature.



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